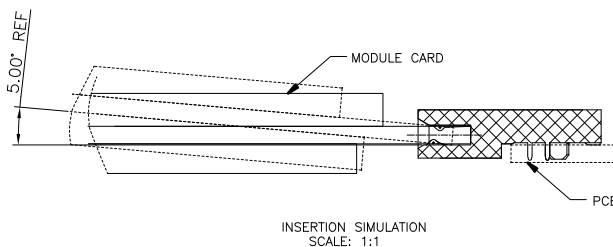
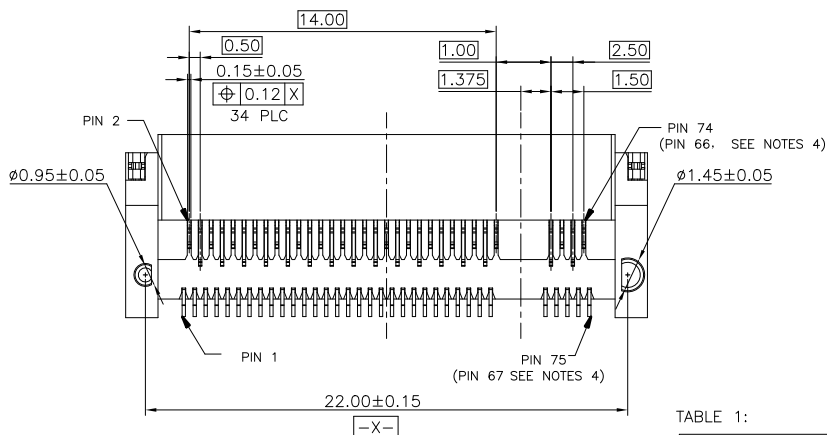
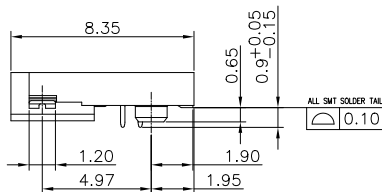
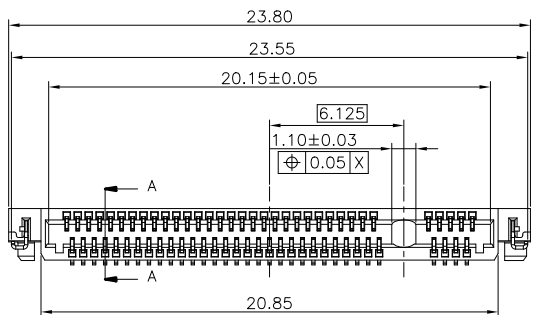
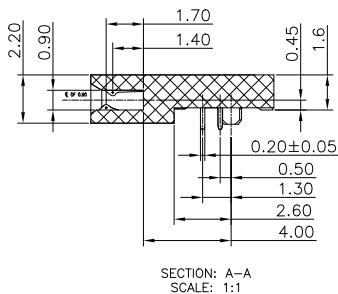
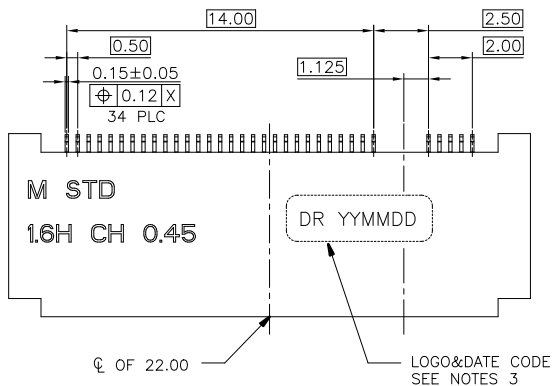


REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
A			INITIAL RELEASE	2023.11.09	Sid Guo



NOTES:
PRODUCT MUST MEET CONTROLLED SUBSTANCES SPEC. ROHS 2.0 AND MEET DEREN CONTROLLED SUBSTANCES SPEC PER WI-PB-S-010

1.MATERIAL:

- 1.1 HOUSING:LCP, UL94V.0; COLOR: BLACK
- 1.2 CONTACT PHOSPHOR BROZNE.
- 1.3 SOLDER PEG AND LATCH:STAINLESS STEEL.

2.FINISH:

- 2.1 CONTACT: 50u" MIN NICKEL UNDERPLATED ALL OVER. GOLD FLASH PLATING ON SOLDERTAIL. GOLD PLATING (SEE NOTE 9) ON CONTACT AREA.
- 2.2 SOLDER PEG: MATTE TIN 100u" MIN. AND NICKEL 50u" MIN UNDERPLATED.

3.LOGO&DATE CODE:

- LOGO: DR OR DEREN
DATECODE: YYWDXL
YY: YEAR (09: 2009)
WW: WEEK (25: THE 25TH WEEK)
D: DAY (1~7: SUNDAY~SATURDAY)
L: LINE NUMBER OF ASSEMBLY (A: LINE A)
X: MANUFACTURE CODE

4.REFLOW SOLDER CAPABLE TO 260°C 10 SEC.

5.ELECTRICAL CHARACTERISTICS :

- 5.1 CURRENT RATING:0.5AMP.
- 5.2 CONTACT RESISTANCE:55 MILLIOHMS MAX. INITIAL, 20 MILLIOHMS MAX. CHANGE AFTER TEST.
- 5.3 IMPEDANCE: 85±10% OHMS
- 5.4 INSULATION RESISTANCE:500 MEGOHMS MIN. INITIAL 100 OHM MIN. CHANGE AFTER TEST.
- 5.5 DIELECTRICAL WITHSTAND VOLTAGE:300V AC MIN.AT SEA LEVEL.

6.MECHANICAL CHARACTERISTICS:

- 6.1 INSERTION FORCE:20N MAX.PER CONTACT PAIR.
- 6.2 DURABILITY:60 MATING AND UNMATING CYCLES.

7.ENVIRONMENTAL CHARACTERISTICS:

- OPERATING TEMPERATURE RANGE:40°C TO +80°C.

8.RECOMENDED STENCIL THICKNESS:0.12MM MIN.

9.PART NUMBER DESCRIPTION:

40-42569-067 B X R HF

- HALOGEN CODE:
HF:HALOGEN FREE
R: TAPE & REEL PACKING
PLATING CODE:
1: AuGF 2: Au5u"
3: Au10u" 4: Au15u" 5: Au30u"
KEY TYPE:
B: KEY M
PIN NUMBER CODE:
067: 67 PINS

TABLE 1:

PART NUMBER	DESCRIPTION	DIM	TOL	DIM	TOL
40-42569-067B1RHF	Au G/F ON CONTACT AREA	X.	±0.30	X.	±2*
40-42569-067B2RHF	Au 5u" ON CONTACT AREA	.X	±0.25	.X	±1*
40-42569-067B3RHF	Au 10u" ON CONTACT AREA	.XX	±0.20		
40-42569-067B4RHF	Au 15u" ON CONTACT AREA				
40-42569-067B5RHF	Au 30u" ON CONTACT AREA				

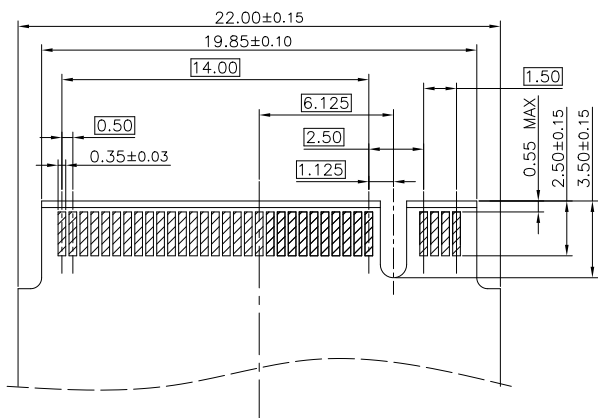


DEREN

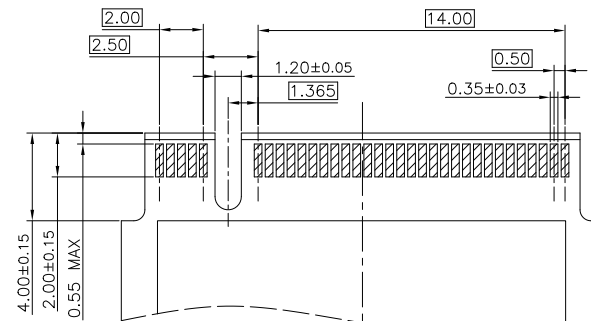
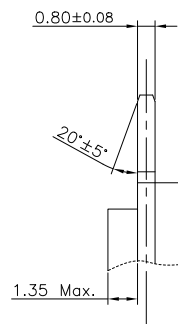
SHENZHEN DEREN ELECTRONIC CO., LTD

C-DWG:	TY	DATE	TITLE: NGFF 1.60H KEY M STD CH 0.45
DESIGN:	Sid Guo	2023.11.09	P/N: SEE TABLE 1
CHECK:	Mike Chen	2023.11.09	SHEET: 1/3
APPROVAL:	Bill Lin	2023.11.09	SCALE: N/A UNIT: mm

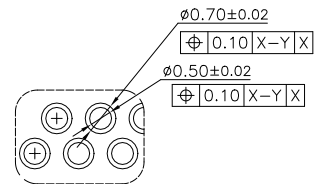
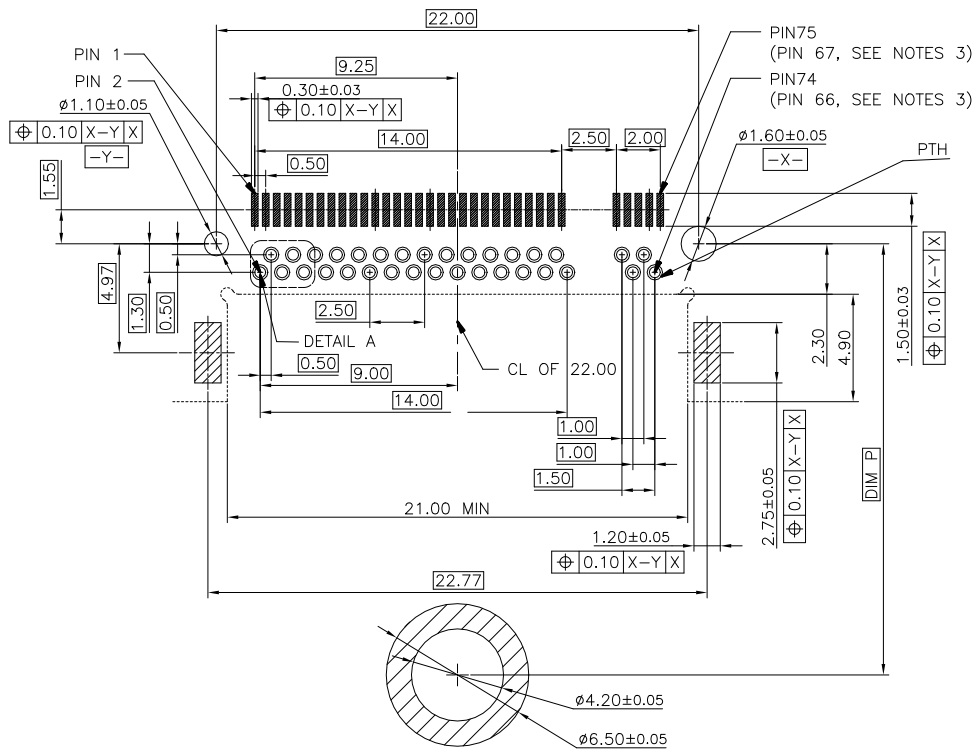
PLUG PCB



BOTTOM SIDE



TOP SIDE



DETAIL A
SCALE: 2:1

22110	114.00
2280	84.00
2260	64.00
2242	46.00
2230	34.00
3042	46.00
3030	34.00
MOUDULE TYPE	DIM P



DEREN

SHENZHEN DEREN ELECTRONIC CO., LTD

DIM	TOL	DIM	TOL		SHENZHEN DEREN ELECTRONIC CO., LTD					
x.	±0.20	x.	±2°		C-DWG:	TY	DATE	TITLE: NGFF 1.60H KEY M STD CH 0.45		
.x	±0.10	.x	±1°		DRAW NO.	DESIGN:	Sid Guo	2023.11.09	P/N: SEE TABLE 1	
.xx	±0.05				SC1600397-1	CHECK:	Mike Chen	2023.11.09	SHEET:	2/3 
					REV.	A	APPROVAL:	Bill Lin	2023.11.09	SCALE: N/A UNIT: mm

RECOMMENDED NGFF PCB LAYOUT(TOP VIEW)

